REMARKS/ARGUMENTS

Pending Claims

Claims 17-22 are pending in this application. Claim 17 has been amended. No new matter has been added.

Claim Rejections under 35 U.S.C. §102

Claims 17-18 and 20 have been rejected under 35 U.S.C. §102(b) as being anticipated by Yamakawa, U.S. Patent No. 6,134,960. Applicants request reconsideration of the rejection in view of the amendments made to claim 17 and for the following reasons.

Claim 17 is directed to an electronic circuit board. Support for the claim is found in Figs. 1 and 2, for example, which show a substrate 1, a circuit conductor layer on a substrate having first and second conductors 3 and 4, and an operational amplifier (Op) that is a monolithic IC and is connected to the circuit conductor layer via conductors 3, 4. As shown in Figs. 1 and 2, the conductor 3 is connected to a positive input of the operational amplifier and the conductor 4 is connected to a negative input of the Op. Claim 17 sets forth a third conductor and an insulating layer that both find support in Fig. 1 as conductor 2 and insulating layer 5, respectively.

As amended, claim 17 sets forth that the circuit conductor layer, the third conductor, and the insulating layer are all disposed on the substrate with the insulating layer disposed between the circuit conductor layer and the third conductor, as shown in Fig. 2. In addition to the insulating layer being disposed between the circuit conductor layer and the third conductor

as set forth in claim 17, the first and second conductors are set forth as being at least partially located below or above the third conductor layer. Further, the third conductor is set forth as not being electrically connected with any part.

By the present invention, both signal conductors 3, 4 of the operational amplifier, which is a monolithic IC, are capacitance-coupled with each other via the conductor 2 as a result of the claimed arrangement. Further, the conductor 2 is not connected electrically to any part. Thus, the claimed combination functions to terminate any AC element. As a result, the electronic circuit board of the present invention has a reduced electromagnetic interference preventing function while being reduced in size and having few components.

In Yamakawa, a thermal type flow sensor is disclosed. The Office Action states that Yamakawa discloses a third conductor layer in Fig. 1B that covers, via an insulating layer, a part of the first conductor in the circuit conductor layer that is connected to a positive input of the operational amplifier, and a part of the second conductor of the circuit conductor layer that is connected to a negative input of the operational amplifier. The Office Action cites col. 9, lines 14-30 of the reference for support of the rejection. However, Applicants respectfully traverse the rejection because the third conductor of Yamakawa is not disposed to overlap the first and second conductors, as in the present invention. As a result, the arrangement of Yamakawa is unable to provide the effect of reducing the electromagnetic interference preventing function as is achieved in the present invention. Accordingly, Yamakawa does not disclose or fairly suggest the invention as set forth in claims 17, 18 and 20. Therefore, the rejection under 35 U.S.C. §102(b) should be withdrawn.

Claim Objections

Claims 19, 21 and 22, which have been objected to as being dependent upon a rejected base claim, should now be found allowable since each of these claims depends from claim 17 and claim 17 is asserted to be allowable for the foregoing reasons.

CONCLUSION

In view of the foregoing, Applicant respectfully requests that a timely Notice of Allowance be issued in this case.

Respectfully submitted,

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